Procurement and Contracting Services

Request for Proposals for a Wafer Level Probe Station

ADDENDUM #1

Sealed RFP # S192526
Due on September 12, 2025 no later than 2:00 PM, MST

The timeline for RFP S192526 has been amended as follows:

Section 3.3:

Original Schedule

08/15/2025	Issuance of RFP
08/21/2025	Technical Questions/Inquiries due no later than 12:00 PM, MST
09/04/2025	RFP is Due September 4, 2025, no later than 2:00 PM, MST

Revised to:

08/15/2025	Issuance of RFP
08/21/2025	Technical Questions/Inquiries due no later than 12:00 PM, MST
09/12/2025	RFP is Due September 12, 2025, no later than 2:00 PM, MST

The following questions were received prior to the technical question period close of August 21, 2025 at 12:00PM MST:

1. 40x objectives are a no standard request, and not available, will 20 or 50x be acceptable alternatives

   Both 20x and 50x should work well. Ideally, having access to both would be preferred.

2. Is there a low noise specification for the 200mm wafer stage?

   There is no specific low-noise specification for the 200mm wafer stage.

3. What type (make & model(s)) of test equipment with the 4 probe positioners be connected to?

   We plan to connect them to the standard version of this model:
   Keysight B1500A Semiconductor Device Parameter Analyzer

4. What type of measurement(s) will the 4 probe positioners be required to perform?
   - DC/CV: Both DC and CV measurements
   - RF: No RF measurements are planned

5. If RF, is there information regarding:
   - Pad layout
   - Pad sizes
   - Material type
   - Probe type (ground-signal, signal-ground, ground-signal-ground, or other)
   - Probe pitch

   Not applicable since RF measurements are not required.

6. Is there an outline of what is considered consumable?

   N/A

End of addendum, all else remains the same.